



566.38683CX1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Masato YOSHIDA, et al.
Serial No.: 10/042,271
Filed: January 11, 2002
For: ABRASIVE METHOD OF POLISHING TARGET MEMBER AND
PROCESS FOR PRODUCING SEMICONDUCTOR DEVICE
Group: 3723
Examiner: Shantese L. McDonald

TERMINAL DISCLAIMER

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RECEIVED

May 28, 2004

JUN 07 2004

Sir: **TECHNOLOGY CENTER R3700**

Petitioner, Hitachi Chemical Company, Ltd., having its place of business at 1-1, Nishishinjuku 2-chome, Shinjuku-ku, Tokyo, Japan, represents that it is the sole owner of the entire interest of U.S. Application Serial No. 10/042,271, filed January 11, 2002, for ABRASIVE METHOD OF POLISHING TARGET MEMBER AND PROCESS FOR PRODUCING SEMICONDUCTOR DEVICE, and that the Assignment of all rights in connection therewith has been recorded at Reel 011094, Frame 0768.

Petitioner hereby disclaims all that portion of the term of any patent to be issued on the above-identified application subsequent to the expiration date of the full statutory term, defined in 35 U.S.C. 154 to 156 and 173, of U.S. Patent